

DECLARATION OF INVENTOR FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: METHODS FOR FORMING AND INTEGRATED CIRCUIT STRUCTURES CONTAINING RUTHENIUM AND TUNGSTEN CONTAINING LAYERS, the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

PRIOR FOREIGN APPLICATIONS:

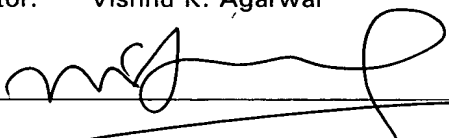
I hereby state that no applications for foreign patents or inventor's certificates have been filed prior to the date of execution of this declaration.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued therefrom.

* * * * *

Full Name of Sole or first Inventor: Vishnu K. Agarwal

Inventor's Signature



3rd May, 2000

Date

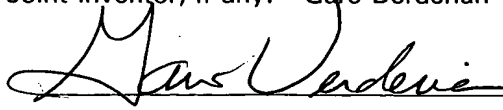
Residence: Boise, Idaho

Citizenship: India

Post Office Address: 2382 East Red Cedar Lane
Boise, Idaho 83716

Full Name of Second Joint Inventor, if any: Garo Derderian

Inventor's Signature



5/1/00

Date

Residence: Boise, Idaho

Citizenship: U.S.A.

Post Office Address: 6184 South Schooner Place
Boise, Idaho 83716

Full Name of Third Joint Inventor, if any: Gurtej S. Sandhu

Inventor's Signature



5/2/00

Date

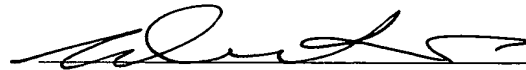
Residence: Boise, Idaho

Citizenship: U.K.

Post Office Address: 2964 E. Parkriver Drive
Boise, Idaho 83706

Full Name of Fourth Joint Inventor, if any: Weimin M. Li

Inventor's Signature



5/1/2000

Date

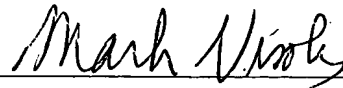
Residence: Boise, Idaho

Citizenship: Republic of China

Post Office Address: 14124 West Chadford
Boise, Idaho 83713

Full Name of Fifth Joint Inventor, if any: Mark Visokay

Inventor's Signature



4/29/00

Date

Residence: ~~Boise, Idaho~~ ^MRichardson Texas

Citizenship: U.S.A.

Post Office Address: ~~4056 S. Federal Way, #G-102~~
^MBoise, Idaho 837162705 Millwood Drive
Richardson Texas 75082

Full Name of Sixth Joint Inventor, if any: Cem Basceri

Inventor's Signature

Cem Basceri

5/1/00
Date

Residence: Boise, Idaho

Citizenship: Turkey

Post Office Address: 314 E. Iowa Dr.
Boise, Idaho 83706

Full Name of Seventh Joint Inventor, if any: Sam Yang

Inventor's Signature

Sam Yang

4/3/00
Date

Residence: Boise, Idaho

Citizenship: Republic of China

Post Office Address: 5923 S. Sweet Gum Way
Boise, Idaho 83716